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(54) Title: PACKAGING SUBSTRATE AND SEMICONDUCTOR STRUCTURE HAVING SAME

(54) 发明名称: 封装基板及其具有的半导体结构

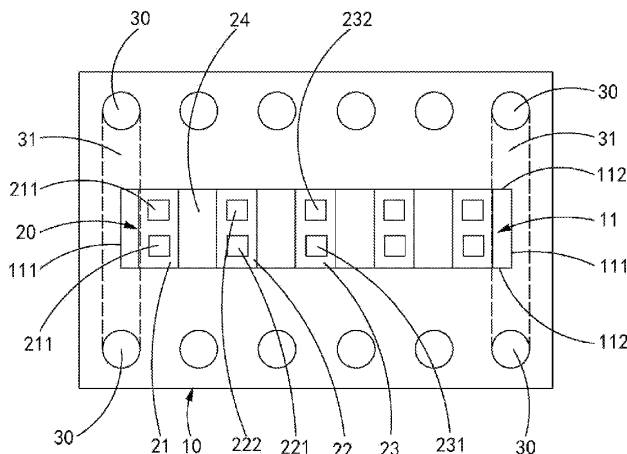


图1

(57) Abstract: The present disclosure relates to the technical field of semiconductors and provides a packaging substrate and a semiconductor structure having same. The packaging substrate comprises a body and an electrically-conductive layer. The body comprises an open area. The electrically-conductive layer is provided in the open area. The electrically-conductive layer comprises a first electrically-conductive bridge and a second electrically-conductive bridge. The first electrically-conductive bridge and the second electrically-conductive bridge are provided at an interval. A first through hole is provided on the first electrically-conductive bridge. With the first electrically-conductive bridge and the second electrically-conductive bridge provided at an interval in the open area, the quality of signal transmission of the electrically-conductive layer is enhanced, and the twist resistance of the body is enhanced by controlling the width of the first electrically-conductive bridge and that of the second electrically-conductive bridge; moreover, with the first through

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hole provided on the first electrically-conductive bridge, the overall area of the electrically-conductive layer is reduced, thus mitigating the problem of warping occurring on the body, and structurally improving the use performance of the packaging substrate.

(57) 摘要: 本公开涉及半导体技术领域, 提出了一种封装基板及具有其的半导体结构。封装基板包括本体和导电层, 本体包括开口区域; 导电层设置于开口区域, 导电层包括第一导电桥和第二导电桥, 第一导电桥和第二导电桥间隔设置; 其中, 第一导电桥上设置有第一通孔。开口区域内设置有相间隔的第一导电桥和第二导电桥, 能够增强导电层信号传输品质, 并能够通过控制第一导电桥和第二导电桥的宽度来增加本体的抗扭曲能力, 而通过在第一导电桥上设置有第一通孔可以降低导电层的总体面积, 以此降低本体出现的翘曲问题, 从结构上改善封装基板的使用性能。